



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

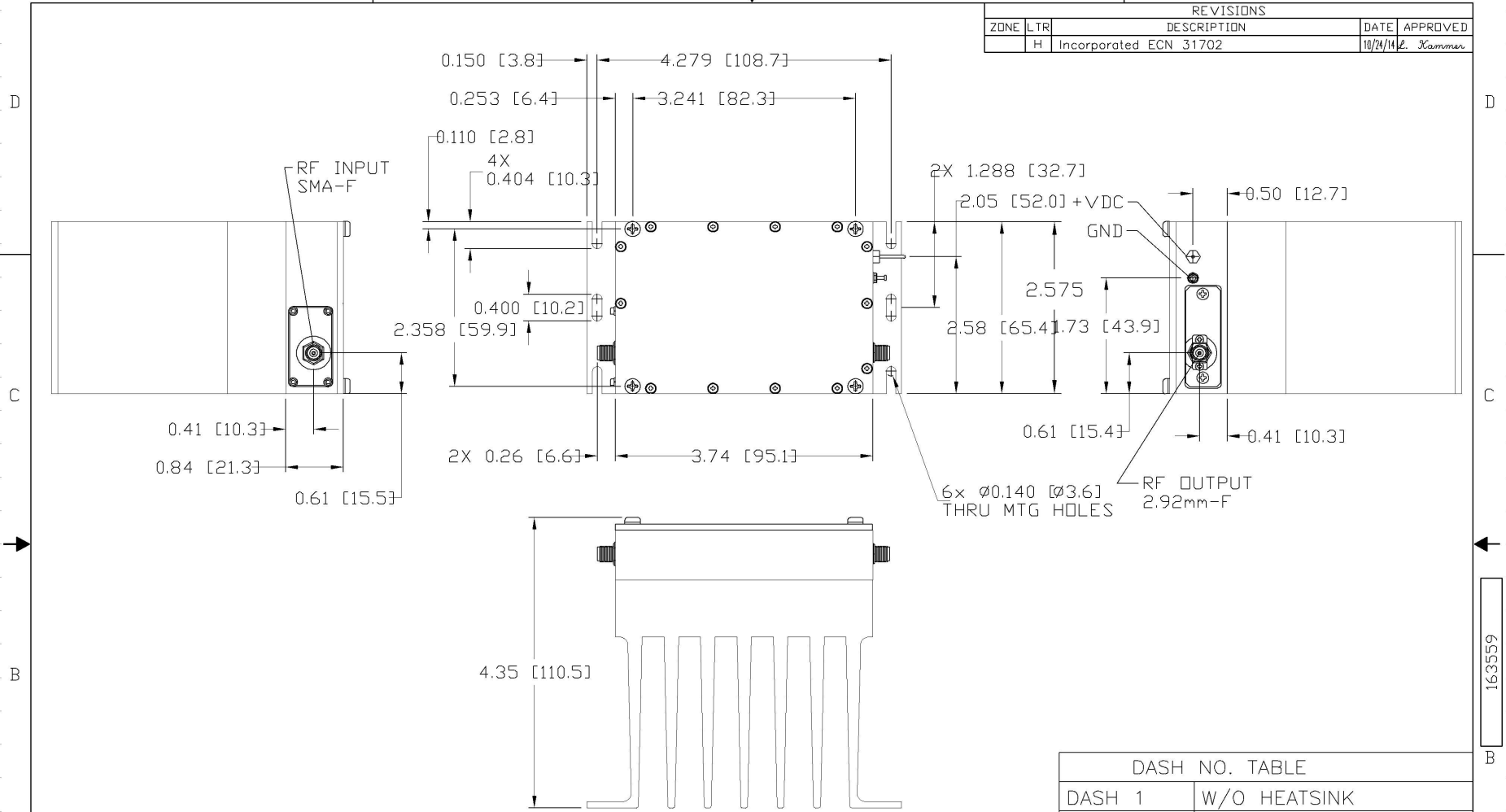
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REVISIONS			
ZONE	LTR	DESCRIPTION	DATE APPROVED
	H	Incorporated ECN 31702	10/24/14 <i>L. Kammer</i>



DASH NO. TABLE	
DASH 1	W/O HEATSINK
DASH 2	WITH HEATSINK

-5	-4	-3	-2	-1	NOMENCLATURE OR DESCRIPTION	SYM/NOTES	PART NO.	CODE IDENT.	ITEM NO.	
QTY REQ'D					PARTS LIST					
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON					DRN BY: <i>E. Marty</i> DATE: 08/15/05 CHK BY: <i>L. Kammer</i> DATE: 11/12/14 APPROVED BY:		100 Davids Drive, Hauppauge, New York 11788			
DECIMALS .XX±01 ANGLES .XXX±.005 ±0°30'					PROJ ENGR: <i>John Sepulveda</i> DATE: 11/14/14 ENG SECT: _____ D.A.: _____		OUTLINE, POWER AMPLIFIER, 2-18 GHz			
MARKING 209201					FINISH		SIZE CODE IDENT. NO		REV.	
PLATE, ANGLE 165383					HEAT TREAT		C 33592 163559		H	
PLATE, CONN. 165236							SCALE REF		SHEET 1 OF 1	
CVR., TOP 165235										
HSG. 165234										
NEXT ASSY USED ON										
APPLICATION										

NOTE:  
HEATSINK MAY BE POSITIONED ON THE COVER OR BASE OF AMPLIFIER.